



Material Content Data Sheet



Sales Product Name		BFR 840L3RHESD E6327		Issued		29. August 2013		
MA#		MA000997852						
Package		PG-TSLP-3-9		Weight*		0.50 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.14		1399	
	noble metal	gold	7440-57-5	0.003	0.54		5426	
	inorganic material	silicon	7440-21-3	0.020	4.02	4.70	40208	47033
leadframe	non noble metal	nickel	7440-02-0	0.131	26.12	26.12	261160	261160
wire	noble metal	gold	7440-57-5	0.009	1.73	1.73	17275	17275
encapsulation	organic material	carbon black	1333-86-4	0.003	0.62		6190	
	plastics	epoxy resin	-	0.042	8.36		83556	
	inorganic material	silicondioxide	60676-86-0	0.266	52.91	61.89	529185	618931
leadfinish	noble metal	gold	7440-57-5	0.011	2.11	2.11	21118	21118
plating	noble metal	silver	7440-22-4	0.017	3.45	3.45	34483	34483
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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